

# GC49C501G1-SJ20I

## *4-bit Turbo Microcontroller*

---

*CORERIVER Semiconductor reserves the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time.*

- ◆ *To discontinue any product or service, CORERIVER should inform customers of that before 3 months through its homepage.*
- ◆ *Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete.*
- ◆ *The CORERIVER Semiconductor products listed in this document are intended for usage in general electronics applications. These CORERIVER Semiconductor products are neither intended nor warranted for usage in equipment that requires extraordinarily high quality and/or reliability or a malfunction or failure of which may cause loss of human life or bodily injury.*

**Copyright CORERIVER Semiconductor Co., Ltd. 2012**

**All Rights Reserved**

# 1 GC49C501G1-SJ20I Overview

## 1.1 General Description

**GC49C501G1-SJ20I** is a 4-bit reduced 8051 Microcontroller.

**GC49C501G1-SJ20I** has 14 programmable I/O ports, Watchdog timer, POR (Power-On Reset), built-in I.R. LED Driver, and LVD (Low Voltage Detector) as peripherals. In addition, it contains an internal ring oscillator, which can generate the 8 MHz system clock signal instead of a crystal oscillator.

**GC49C501G1-SJ20I** operates over the extended -40°C to +85°C temperature range, and is available in the 20-pin SOP package.

## 1.2 Features

- ◆ CPU
  - ✓ 4-bit reduced 8051 architecture
  - ✓ Continuous program addressing, not paged.
  - ✓ 51 instructions including push, pop and logic inst.
  - ✓ Instruction cycle :  $F_{SYS}/6$
  - ✓ Multi-level subroutine nesting with RAM based stack.
- ◆ On-chip Memories
  - ✓ FLASH : 1024 bytes (including 128 EEPROM)
  - ✓ RAM : 64 nibbles (including stack)
- ◆ ISP (In System Programming) of FLASH
- ◆ IAP (In Application Programming) of FLASH
- ◆ I/O Ports
  - ✓ P0 : 4-bit parallel I/O (Open drain output)
  - ✓ P1 : Parallel I/O (Open drain output) 2-bit
  - ✓ P2, P3 : 4-bit parallel/bit-selectable I/O (Open drain output)
- ◆ REM output (Remote control transmitter)
  - ✓ Built-in Transistor for I.R. LED Drive

- ✓  $I_{OL} = 300 \text{ mA (Max.)}$  at  $V_{DD} = 3\text{V}$  and  $V_O = 0.4\text{V}$
- ◆ Carrier Pulse Generation : 7 types
- ◆ Built-in Oscillator
  - ✓ Crystal/Ceramic resonator
  - ✓ Internal oscillator : 8MHz
- ◆ Built-in Reset
  - ✓ Power-on Reset, Power-fail Reset
  - ✓ WDT (Watch-Dog Timer) Reset
  - ✓ Clock switching reset
- ◆ Power Management
  - ✓ Power-down (stop) mode
  - ✓ Release stop by input changes
  - ✓ Sleep mode
- ◆ Power Consumption
  - ✓ Stop mode :  $< 0.1\mu\text{A (Typ.)}$  at 2.0V  
 $1 \mu\text{A (Max.)}$  at 5.0V
  - ✓ Normal mode :  $400 \mu\text{A (Typ.)}$  at 2.0V,  $F_{SYS} = 4 \text{ MHz}$
- ◆ Operating frequency vs. voltage
  - ✓ Max.  $F_{OSC} = 10 \text{ MHz}$  ( $2.7 \text{ V} \leq V_{DD} \leq 5.5\text{V}$ )
  - ✓ Max.  $F_{OSC} = 5 \text{ MHz}$  ( $1.8 \text{ V} \leq V_{DD} < 2.7\text{V}$ )
- ◆ Operating temperature :  $-40 \text{ }^\circ\text{C} \sim 85 \text{ }^\circ\text{C}$
- ◆ ESD protection
  - ✓ HBM : 2,000V (JESD22-A114E)
  - ✓ MM : 200V (JESD22-A115-A)
  - ✓ CDM : 800V (JESD22-C101-C)
- ◆ Latch-up protection up to  $\pm 200\text{mA}$
- ◆ Package
  - ✓ 20-pin SOIC (JEDEC)

### 1.3 Applications

- ◆ Remote Controller

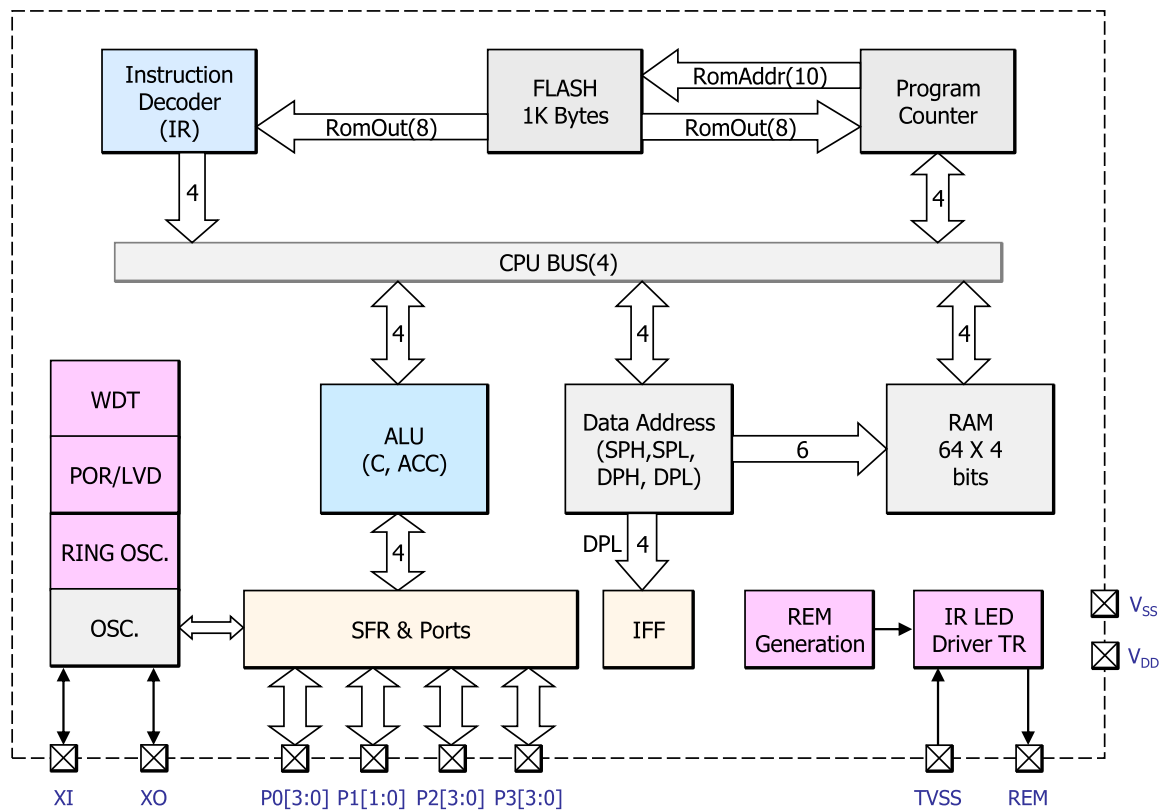
## 1.4 Product Family Guide

Product	Mask-ROM [Byte]	Flash (EEPROM) [Byte]	RAM [Nibble]	Package	I/O Pins	Other Peripherals
GC49C501G1-SO24I	-	1k (128)	64	24-SOIC	18	WDT IAP ISP LVD POR Ring Oscillator I.R. LED Driver
<b>GC49C501G1-SJ20I</b>	-	<b>1k (128)</b>	<b>64</b>	<b>20-SOIC (JEDEC)</b>	<b>14</b>	
GC41C501G1-SO24I	1k	-	64	24-SOIC	18	
GC41C501G1-SJ20I	1k	-	64	20-SOIC (JEDEC)	14	

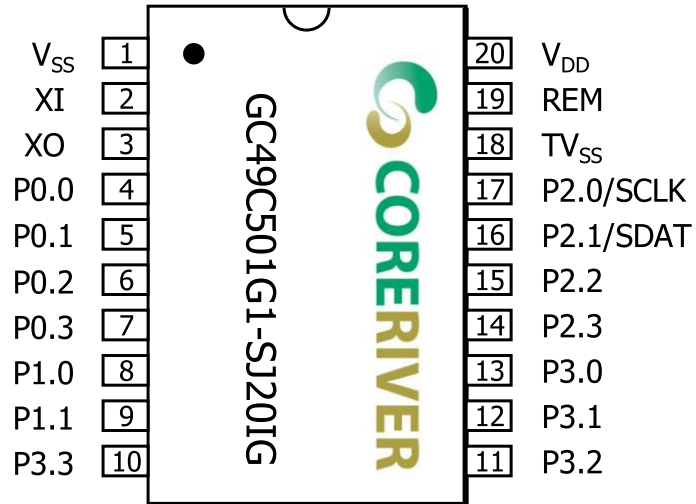
## 2 Block Diagram

Figure shows the block diagram of **GC49C501G1-SJ20I**. Programs reside in the internal program memory (Embedded Flash Memory). Data are read from or written to data memory (SRAM) or special function registers (SFRs).

The internal registers of **GC49C501G1-SJ20I** are configured as part of the on-chip RAM: therefore each register has an address.



### 3 Pin Configuration



24-pin SOIC Package Diagram

## 4 Pin Description

Pin No.	Name	Type	Description	Share Pins
1	V <sub>SS</sub>	GND	Ground	
2	XI	Input	Input to the inverting oscillator amplifier.	
3	XO	Output	Output from the inverting oscillator amplifier.	
4	P0.0	I/O	General I/O	
5	P0.1	I/O	General I/O	
6	P0.2	I/O	General I/O	
7	P0.3	I/O	General I/O	
8	P1.0	I/O	General I/O	
9	P1.1	I/O	General I/O	
10	P3.3	I/O	General I/O	
11	P3.2	I/O	General I/O	
12	P3.1	I/O	General I/O	
13	P3.0	I/O	General I/O	
14	P2.3	I/O	General I/O	
15	P2.2	I/O	General I/O	
16	P2.1	I/O	General I/O	SDAT
17	P2.0	I/O	General I/O	SCLK
18	TV <sub>SS</sub>	GND	Ground for IR LED drive Transistor	
19	REM	Output	Output for IR LED drive Transistor. The transistor is n-channel device.	
20	V <sub>DD</sub>	PWR	Power Supply	

## 5 Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
$V_{DD}$	DC supply voltage	-0.5 to 6.5V	V
$V_{IN}$	DC input voltage	-0.5 to $V_{DD} + 0.5$	V
$V_{OUT}$	DC output Voltage	-0.5 to $V_{DD} + 0.5$	V
$I_{OH}$	DC output high current	One I/O pin active: -25	mA
		All I/O pins active: -100	mA
$I_{OL}$	DC output low current	One I/O pin active: 30	mA
		All I/O pins active: 150	mA
$T_{STG}$	Storage temperature	-55 to 125	°C

## 6 Recommended Operating Conditions

Symbol	Parameter	Rating	Unit
$V_{DD}$	DC supply voltage	1.8 to 5.5	V
$T_A$	Industrial temperature range	-40 to 85	°C



## 7 DC Characteristics

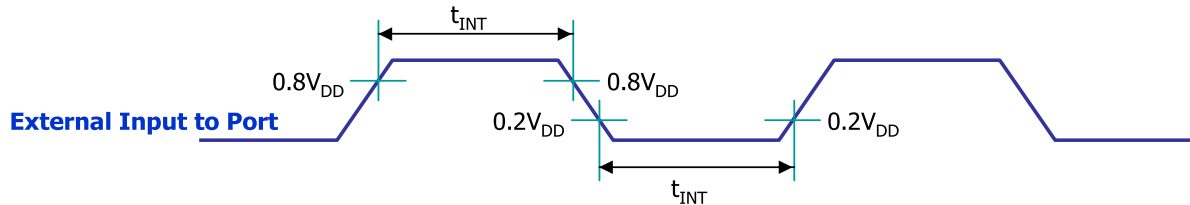
( $T_A = -40^{\circ}\text{C} \sim +85^{\circ}\text{C}$ ,  $V_{DD} = 1.8\text{V} \sim 5.5\text{V}$  unless otherwise specified)

Parameter	Symbol	Pin	Conditions	Value			Unit
				Min.	Typ.	Max.	
Input low voltage	$V_{IL1}$	P0, P1, P2, P3	$V_{DD} = 1.8\text{V} \sim 5.5\text{V}$	-0.5	-	$0.2V_{DD} - 0.1$	V
Input high voltage	$V_{IH1}$	P0, P1, P2, P3	$V_{DD} = 1.8\text{V} \sim 5.5\text{V}$	$0.2V_{DD} + 1.0$	-	$V_{DD} + 0.5$	V
Input high leakage current	$I_{IH}$	All pins except XI, XO	$V_{IN} = V_{DD}$	-1	-	+1	$\mu\text{A}$
Output low voltage	$V_{OL}$	P0,P1,P2,P3	$I_{OL} = 20\text{mA} @ V_{DD} = 5\text{V}$ ( $I_{OL} = 3\text{mA} @ V_{DD} = 2.2\text{V}$ )	-	-	$0.3V_{DD}$	V
Output low voltage	$V_{OL2}$	REM	$I_{OL} = 280\text{mA} @ V_{DD} = 3\text{V}$	-	-	0.4	V
Output high voltage	$V_{OH}$	P2 (push-pull output)	$I_{OH} = -15\text{mA} @ V_{DD} = 5\text{V}$	$0.7V_{DD}$	-	-	V
Output high voltage	$V_{OHP}$	Pull-up current	$I_{OHP} = -40\mu\text{A} @ V_{DD} = 5\text{V}$ ( $I_{OHP} = -15\mu\text{A} @ V_{DD} = 2.2\text{V}$ )	$0.7V_{DD}$	-	-	V
Pin capacitance	$C_{IO}$	All	$V_{DD} = 5\text{V}$	-	10	-	pF

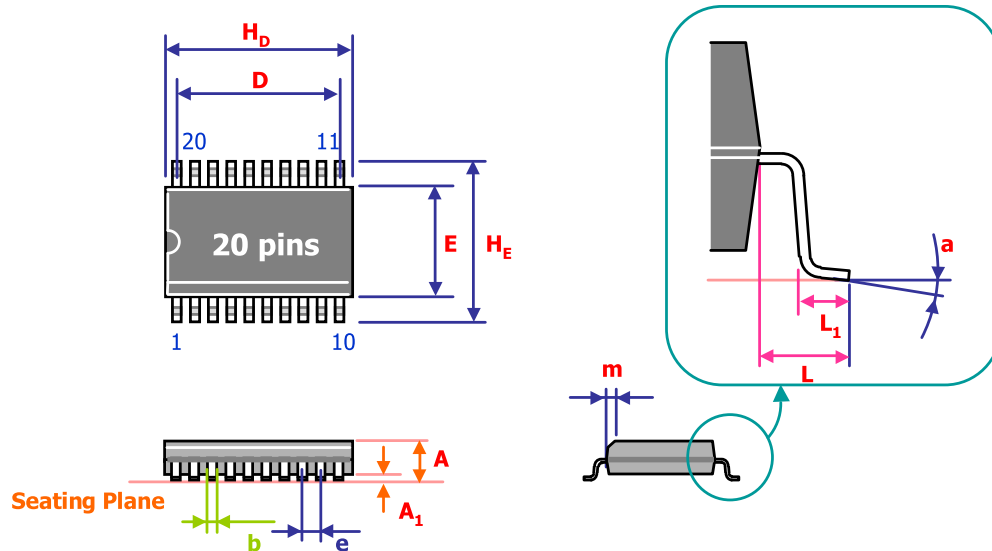
## 8 AC Characteristics

( $T_A = -40^\circ\text{C} \sim +85^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Pin	Conditions	Value			Unit
				Min.	Typ.	Max.	
Operating Frequency (Internal Clock)	$F_{\text{OSC}}$		$2.7\text{V} \leq V_{\text{DD}} \leq 5.5\text{V}$	-	-	10	MHz
			$1.8\text{V} \leq V_{\text{DD}} \leq 2.7\text{V}$	-	-	5	
Operating Frequency (External Clock)	$F_{\text{OSC}}$	XI, XO	$2.7\text{V} \leq V_{\text{DD}} \leq 5.5\text{V}$	-	-	10	MHz
			$1.8\text{V} \leq V_{\text{DD}} \leq 2.7\text{V}$	-	-	5	
System Frequency	$F_{\text{SYS}}$		$1.8\text{V} \leq V_{\text{DD}} \leq 5.5\text{V}$	1/64	-	1	$F_{\text{OSC}}$
External Input Width	$t_{\text{INT}}$	P0, P1, P2, P3	$1.8\text{V} \leq V_{\text{DD}} \leq 5.5\text{V}$	12	-	-	$F_{\text{SYS}}$



## 9 20-pin SOIC Package Dimension



Symbol	Dimension in Inches			Dimension in mm		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	-	-	0.106	-	-	2.7
$A_1$	0.004	-	-	0.1	-	-
b	0.013	0.016	0.020	0.324	0.4	0.51
E	0.264	0.295	0.324	6.71	7.5	8.23
$H_D$	0.495	0.504	0.512	12.57	12.8	13
$H_E$	0.394	0.406	0.419	10.0	10.3	10.643
L	0.016	-	0.052	0.406	-	1.32
a	0°	-	8°	0°	-	8°
e	0.050 BSC			1.27 BSC		

### Notes:

1. Dimension D & E include mold mismatch and are determined at the mold parting line.
2. General appearance spec. should be based on final visual inspection spec.